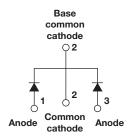


# HEXFRED® Ultrafast Soft Recovery Diode, 2 x 8 A



D<sup>2</sup>PAK (TO-263AB)



PRIMARY CHARACTERISTICS						
I <sub>F(AV)</sub>	2 x 8 A					
$V_{R}$	600 V					
V <sub>F</sub> at I <sub>F</sub>	1.4 V					
t <sub>rr</sub> typ.	18 ns					
T <sub>J</sub> max.	150 °C					
Package	D <sup>2</sup> PAK (TO-263AB)					
Circuit configuration	Common cathode					

#### **FEATURES**

- Ultrafast and ultrasoft recovery
- Very low I<sub>RRM</sub> and Q<sub>rr</sub>
- · Specified at operating conditions
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C





RoHS

#### HALOGEN FREE

#### **BENEFITS**

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- · Reduced parts count

#### **DESCRIPTION**

VS-HFA16TA60CS is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 8 A per leg continuous current, the VS-HFA16TA60CS is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I<sub>RRM</sub>) and does not exhibit any tendency to "snap-off" during the tb portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA16TA60CS is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

ABSOLUTE MAXIMUM RATINGS								
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS				
Cathode to anode voltage	$V_R$		600	V				
Maximum continuous forward current per leg	-	T <sub>C</sub> = 100 °C	8	1				
per device	l <sub>F</sub>	1 <sub>C</sub> = 100 C	16	^				
Single pulse forward current	I <sub>FSM</sub>		60	А				
Maximum repetitive forward current	I <sub>FRM</sub>		24					
Movimum novey discipation	р	T <sub>C</sub> = 25 °C	36	W				
Maximum power dissipation	$P_{D}$	T <sub>C</sub> = 100 °C	14	VV				
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +150	°C				



<b>ELECTRICAL SPECIFICATIONS PER LEG</b> (T <sub>J</sub> = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS		
Cathode to anode breakdown voltage	V <sub>BR</sub>	Ι <sub>R</sub> = 100 μΑ			-	-			
		I <sub>F</sub> = 8.0 A		ı	1.4	1.7	V		
Maximum forward voltage	$V_{FM}$	I <sub>F</sub> = 16 A	See fig. 1	-	1.7	2.1			
		I <sub>F</sub> = 8.0 A, T <sub>J</sub> = 125 °C		-	1.4	1.7			
Maximum reverse leakage current	I <sub>RM</sub>	V <sub>R</sub> = V <sub>R</sub> rated	See fig. 2	-	0.3	5.0			
Maximum reverse leakage current		$T_J = 125$ °C, $V_R = 0.8 \times V_R$ rated	See lig. 2	-	100	500	μA		
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 200 V See fig. 3		-	10	25	pF		
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body - 8.0 -				nH			

DYNAMIC RECOVERY CHARACTERISTICS PER LEG (T <sub>J</sub> = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS		
	t <sub>rr</sub>	$I_F = 1.0 \text{ A}, dI_F/dt = 200$	A/ $\mu$ s, $V_R = 30 \text{ V}$	-	18	-			
Reverse recovery time See fig. 5, 6 and 16	t <sub>rr1</sub>	T <sub>J</sub> = 25 °C		-	37	55	ns		
geo ng. e, e ana re	t <sub>rr2</sub>	T <sub>J</sub> = 125 °C		-	55	90			
Peak recovery current	I <sub>RRM1</sub>	T <sub>J</sub> = 25 °C		-	3.5	5.0	Α		
See fig. 7 and 8	I <sub>RRM2</sub>	T <sub>J</sub> = 125 °C	I <sub>F</sub> = 8.0 A dI <sub>F</sub> /dt = 200 A/µs	-	4.5	8.0			
Reverse recovery charge	Q <sub>rr1</sub>	T <sub>J</sub> = 25 °C	$V_{\rm R} = 200 \text{ V}$	-	65	138	nC		
See fig. 9 and 10	Q <sub>rr2</sub>	T <sub>J</sub> = 125 °C	] "	-	124	360	110		
Peak rate of fall of recovery current	dI <sub>(rec)M</sub> /dt1	T <sub>J</sub> = 25 °C		-	240	-	Λ/μο		
during t <sub>b</sub> , see fig. 11 & 12	dI <sub>(rec)M</sub> /dt2	T <sub>J</sub> = 125 °C		-	210	-	- A/μs		

THERMAL - MECHANICA	THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Lead temperature	T <sub>lead</sub>	0.063" from case (1.6 mm) for 10 s	-	-	300	°C			
Junction to case, single leg conducting	В		-	-	3.5				
Junction to case, both legs conducting	R <sub>thJC</sub>		-	-	1.75	K/W			
Thermal resistance, junction to ambient	R <sub>thJA</sub>	Typical socket mount	-	-	80				
Weight			-	2	-	g			
vveignt			-	0.07	-	oz.			
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)			
Marking device		Case style D <sup>2</sup> PAK (TO-263AB)	HFA16TA60CS						

### www.vishay.com Vishay Semiconductors

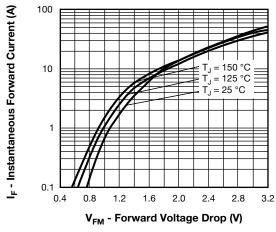


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

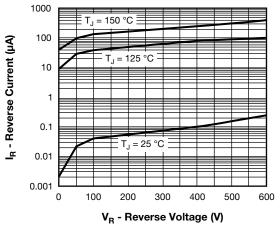


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

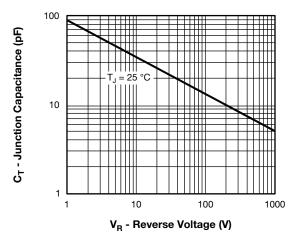


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

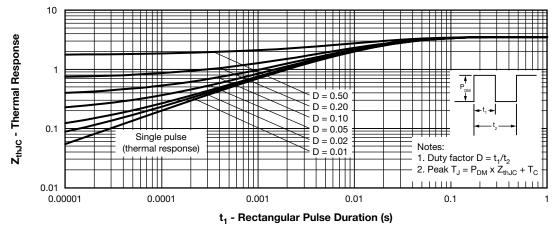


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics (Per Leg)

### www.vishay.com

### Vishay Semiconductors

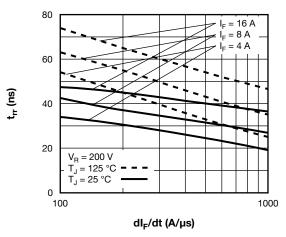


Fig. 5 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt (Per Leg)

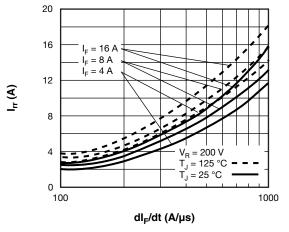


Fig. 6 - Typical Recovery Current vs. dl<sub>F</sub>/dt (Per Leg)

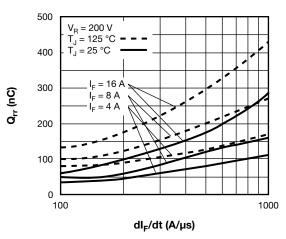


Fig. 7 - Typical Stored Charge vs. dl<sub>F</sub>/dt (Per Leg)

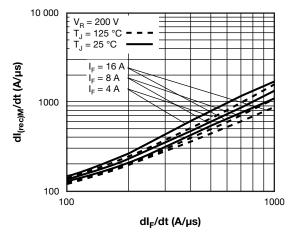
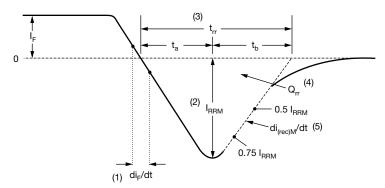


Fig. 8 - Typical dI<sub>(rec)M</sub>/dt vs. dI<sub>F</sub>/dt (Per Leg)



- (1) di<sub>F</sub>/dt rate of change of current through zero crossing
- (2)  $I_{\text{RRM}}$  peak reverse recovery current
- (3)  $\rm t_r$  reverse recovery time measured from zero crossing point of negative going  $\rm I_F$  to point where a line passing through 0.75  $\rm I_{RRM}$  and 0.50  $\rm I_{RRM}$  extrapolated to zero current.
- (4)  $\mathbf{Q}_{\text{rr}}$  area under curve defined by  $\mathbf{t}_{\text{rr}}$  and  $\mathbf{I}_{\text{RBM}}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

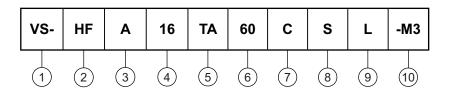
(5) di<sub>(rec)M</sub>/dt - peak rate of change of current during t<sub>b</sub> portion of t<sub>rr</sub>

Fig. 9 - Reverse Recovery Waveform and Definitions



#### **ORDERING INFORMATION TABLE**

### Device code



1 - Vishay Semiconductors product

2 - HEXFRED<sup>®</sup> family

- Process designator: A = electron irradiated

Current rating (16 = 16 A)

- Package outline (TA = TO-220, 3 leads)

• Voltage rating (60 = 600 V)

7 - Circuit configuration (C = common cathode)

8 -  $S = D^2PAK (TO-263AB)$ 

• None = tube (50 pieces)

• L = tape and reel (left oriented)

• R = tape and reel (right oriented)

10 - Environmental digit:

-M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)								
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION					
VS-HFA16TA60CS-M3	50	1000	Antistatic plastic tube					
VS-HFA16TA60CSR-M3	800	800	13" diameter reel					
VS-HFA16TA60CSL-M3	800	800	13" diameter reel					

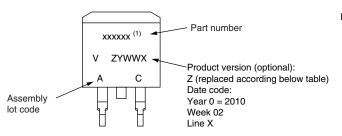
LINKS TO RELATED DOCUMENTS							
Dimensions	www.vishay.com/doc?96164						
Part marking information	www.vishay.com/doc?95444						
Packaging information	www.vishay.com/doc?96424						
SPICE model	www.vishay.com/doc?95689						



# **Part Marking Information**

Vishay Semiconductors

### D<sup>2</sup>PAK



Example: This is a xxxxxx <sup>(1)</sup> with assembly lot code AC, assembled on WW 02, 2010

#### Note

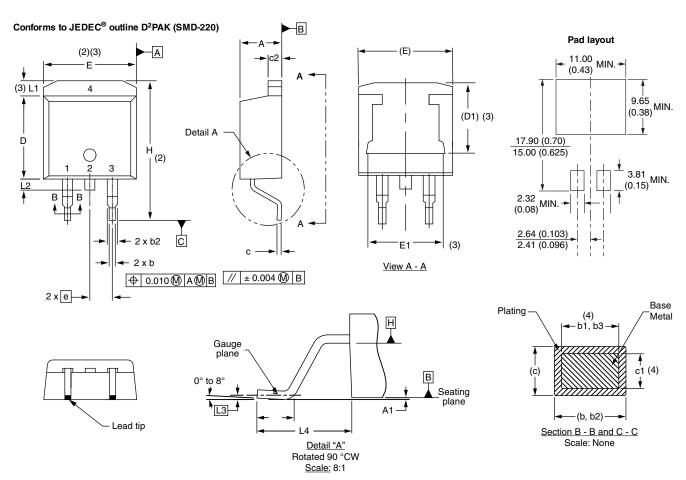
(1) If part number contain "H" as last digit, product is AEC-Q101 qualified

ENVIRONMENTAL NAMING CODE (Z)	PRODUCT DEFINITION				
А	Termination lead (Pb)-free				
В	Totally lead (Pb)-free				
E	RoHS-compliant and termination lead (Pb)-free				
F	RoHS-compliant and totally lead (Pb)-free				
M	Halogen-free, RoHS-compliant, and termination lead (Pb)-free				
N	Halogen-free, RoHS-compliant, and totally lead (Pb)-free				
G Green					



### D<sup>2</sup>PAK

### **DIMENSIONS** in millimeters and inches



SYMBOL	MILLIM	ETERS	INC	HES	NOTES	NOTES S	SYMBOL	MILLIM	ETERS	INC	HES	NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES		STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			E	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100	BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

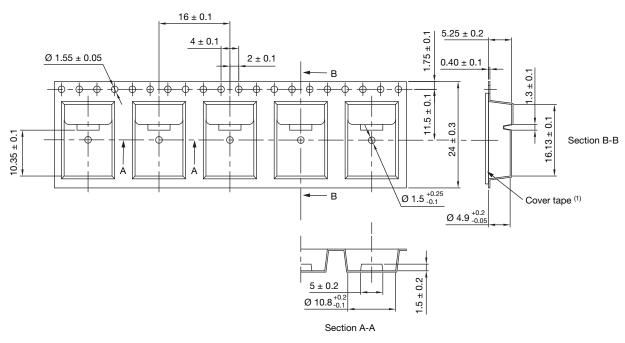
#### Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inches
- (7) Outline conforms to JEDEC® outline TO-263AB

Revision: 13-Jul-17 Document Number: 96164

# D<sup>2</sup>PAK (TO-263AB)

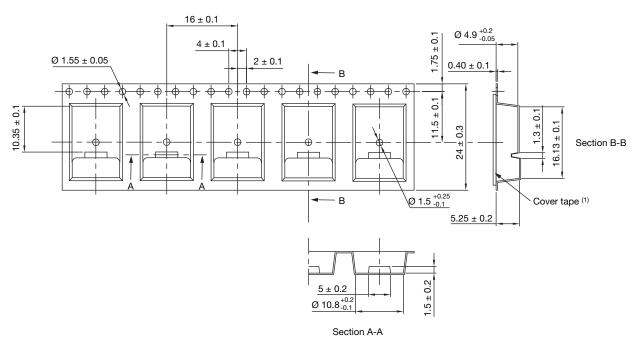
### **CARRIER TAPE FOR TAPE AND REEL LEFT** in millimeters



#### Note

(1) For dimensions, see next pages

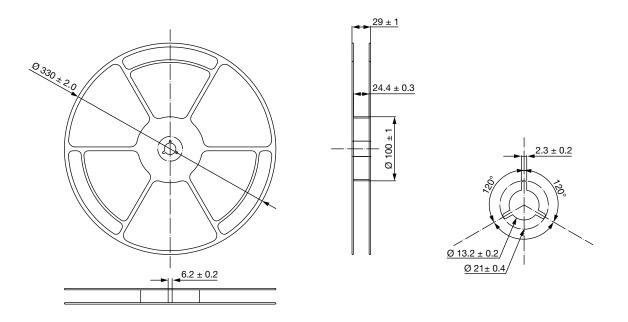
### **CARRIER TAPE FOR TAPE AND REEL RIGHT** in millimeters



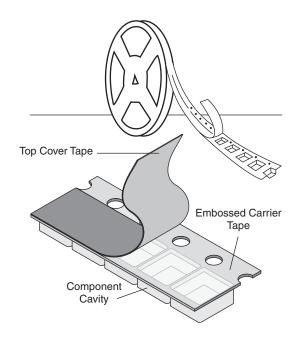
### Note

(1) For dimensions, see next pages

### **REEL FOR CARRIER TAPE** in millimeters



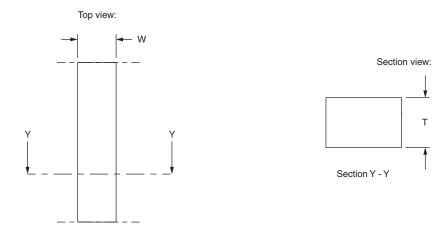
### CARRIER TAPE AND REEL PACKAGING D<sup>2</sup>PAK (TO-263AB)



# **Packaging Information**

Vishay Semiconductors

### **COVER TAPE FOR CARRIER TAPE** in millimeters



APPLICATION	COVER TAPE WIDTH W	COVER TAPE THICKNESS T	CARRIER TAPE WIDTH	MATERIAL
D <sup>2</sup> PAK (TO-263AB)	21.3 ± 0.1	0.060 ± 0.01	24	Antistatic/treated/transparent/polyester



### **Legal Disclaimer Notice**

Vishay

### **Disclaimer**

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.